

CICMT Program Outline	
Monday, April 23	
4:00 pm – 7:00 pm	Registration
6:00 pm - 7:00 pm	Opening Reception
Tuesday, April 24	
7:00 am – 7:30 pm	Registration
10:00 am - 7:30 pm	Exhibit Hours
8:30 am – 9:00 am	Keynote Presentation Title: Piezoelectric MEMS for Molecular Medical Diagnostics Speaker: Wolfgang Rossner, M. Schreiter, Siemens AG, Corporate Technology
9:00 am – 9:30 am	Keynote Presentation Title: Microsystems and Microfluidics: Why not LTCC? Speaker: Amy J. Moll, Boise State University
9:30 am – 10:00 am	Keynote Presentation Title: The Development of Multi-Gigabit Radio Technology for Terabit Wireless Personal Area Networks Speaker: Joy Laskar, Georgia Institute of Technology
10:00 am – 10:30 am	Break in Exhibit Hall
	Ceramic Micro Systems Track
	Ceramic Interconnect Track
Topical Sessions: 10:30 am - 12:10 pm	Session TA1: Materials and Processes for Microsystems Chair: Dan Krueger, Honeywell
	Session TA2: Co-Firing Processes and Dimensional Control in LTCC Chair: Hyo Tae Kim, Korea Institute of Ceramic Engineering & Technology
12:10 pm - 1:20 pm	Lunch in Exhibit Hall
Topical Session: 1:20 pm - 3:00 pm	Session TP1: High Frequency Characterization and Simulation Chairs: Michael Janezic, NIST; Rhonda Franklin Drayton, University of Minnesota
	Session TP2: Ceramic Actuators Chairs: Richard Eitel, University of Kentucky; Clive Randall, The Pennsylvania State University
3:00 pm - 3:30 pm	Break in Exhibit Hall
Topical Session: 3:30 pm - 4:50 pm	Session TP3: Advanced Packaging Technology I Chair: Fred Barlow, University of Idaho
	Session TP4: Direct Write Technology Chairs: Paul Clem, Sandia National Laboratories; Jim Smay, Oklahoma State University
5:00 pm - 7:30 pm	Reception in Exhibit Hall
Wednesday, April 25	
7:00 am - 5:00 pm	Registration
10:00 am - 5:00 pm	Exhibit Hours
8:30 am - 10:00 am	Session WA1: International Session on Microsystems I Chairs: Yong Soo Cho, Yonsei University; Takaaki Tsurumi, Tokyo Institute of Technology
10:00 am - 10:30 am	Break in Exhibit Hall
Topical Sessions: 10:30 am - 12:10 pm	Session WA2: Microsystem Applications Chairs: Karl-Heinz Drue, Technical University of Ilmenau; Hansu Birol, Ecole Polytechnique Fédérale de Lausanne (EPFL)
	Session WA3: Processing and Design of Integrated Passives in LTCC Chairs: Timothy Mobley, DuPont; Jerry Aguirre, Kyocera America Inc.
12:10 pm - 1:20 pm	Lunch in Exhibit Hall
Topical Sessions: 1:20 pm - 3:00 pm	Session WP1: Microsystem Materials and Processes Chair: Ken Peterson, Sandia National Laboratories
	Session WP2: Advanced Packaging Technology II Chairs: Martin Oppermann, EADS Deutschland GmbH; Jouko Vähäkangas, University of Oulu
3:00 pm - 5:00 pm	Session WP3: Interactive Forum (Poster Session) <i>One-on-One Interactive Forum. This is your chance for detailed interaction with authors whose work is too good to miss.</i>
Thursday, April 26	
7:30 am - Noon	Registration
8:30 am - 10:00 am	Session THA1: International Session on Microsystems II Chairs: Jens Mueller, Technical University of Ilmenau; Leszek Golonka, Wroclaw University of Technology
10:00 am - 10:20 am	Break
10:20 am - Noon	Session THA2: Design and Fabrication of Ceramic Microsystems and Devices Chair: Torsten Rabe, Federal Institute for Materials Research and Testing
Noon	Closing Remarks